POLISHING COMPOSITION

ABSTRACT

A polishing composition that allows polishing speed to be increased and surface roughness to be reduced is provided. The polishing composition according to the present invention includes a compound including at least an oxyethylene group or an oxypropylene group in a block polyether represented by the following general formula (1), a basic compound, and abrasives: >N-R-N< (1) where R represents an alkylene group expressed as C_nH_{2n}, and "n" is an integer not less than 1.

No Suitable Figure.